

## **SEMICONDUCTOR PACKAGE WITH EXPOSED DIE PAD AND BODY-LOCKING LEADFRAME**

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### **ABSTRACT OF THE DISCLOSURE**

10 A very thin, small outline, thermally enhanced semiconductor package includes  
a leadframe that is coined to form locking features on an exposed die pad and on a plu-  
rality of extremely narrow, closely spaced leads. The coined features improve the me-  
chanical locking between the leadframe and the plastic body of the package to increase  
their resistance to delamination and subsequent penetration by moisture, and enable  
reliable wire bonds to be made to the otherwise extremely narrow leads.

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